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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

IN RE APPLICATION OF:
Hiroyuki YANO, et al.

PATENT NO.: 6,740,590

: EXAMINER: Duy V. Nguyen DEO

ISSUED: May 25, 2004

:GROUP: 1765

FOR: AQUEOUS DISPERSION, AQUEOUS DISPERSION FOR CHEMICAL
MECHANICAL POLISHING USED FOR MANUFACTURE OF SEMICONDUCTOR
DEVICES, METHOD FOR MANUFACTURE OF SEMICONDUCTOR DEVICES,
AND METHOD FOR FORMATION OF EMBEDDED WIRING.

REQUEST FOR CORRECTED CERTIFICATE OF CORRECTION

HONORABLE COMMISSIONER OF PATENTS & TRADEMARKS
WASHINGTON, DC

SIR:

Attached is a copy of a Certificate of Correction issued in the above-identified Patent. It has been marked-up to indicate errors made by the Patent Office. Also attached is a copy of our Form PTO-1050 as filed on June 10, 2004.

Please issue a correct Certificate of Correction to "supercede" the incorrect one issued on February 15, 2005.

In light of the fact that the errors are the fault of the Patent Office, no fees are required.

Respectfully submitted,

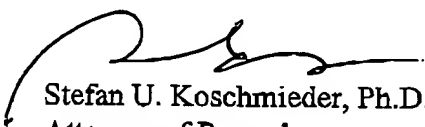
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UNITED STATES PATENT AND TRADEMARK OFFICE
CERTIFICATE OF CORRECTION

PATENT NO.: 6,740,590
DATED: May 25, 2004
INVENTOR(S): Yano et al.

It is certified that an error appears in the above-identified patent and that said Letters Patent is hereby corrected as shown below:

On the title page, Item (54), and in Column 1 the title information should read:

-- (54) **AQUEOUS DISPERSION, AQUEOUS DISPERSION FOR CHEMICAL MECHANICAL POLISHING USED FOR MANUFACTURE OF SEMICONDUCTOR DEVICES, METHOD FOR MANUFACTURE OF SEMICONDUCTOR DEVICES, AND METHOD FOR FORMATION OF EMBEDDED WIRING --**

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UNITED STATES PATENT AND TRADEMARK OFFICE
CERTIFICATE OF CORRECTION

PATENT NO. : 6,740,590 B1
DATED : May 25, 2004
INVENTOR(S) : Yano et al.

Page 1 of 1

It is certified that error appears in the above-identified patent and that said Letters Patent is hereby corrected as shown below:

Title page, Item [54] and Column 1, lines 1-5.

Title, should read:

**– AQUEOUS DISPERSION, AQUEOUS DISPERSION FOR CHEMICAL
MECHANICAL POLISHING USED FOR MANUFACTURE OF
SEMICONDUCTOR DEVICES, METHOD FOR MANUFACTURE OF
SEMICONDUCTOR DEVICES, AND METHOD FOR FORMATION OF
EMBEDDED WIRING –**

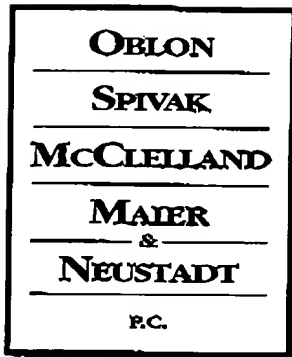
Signed and Sealed this

Fifteenth Day of February, 2005



JON W. DUDAS

Director of the United States Patent and Trademark Office



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MESSAGE

Please see the attached Request for Corrected Certificate of Correction.

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